

Product Information Sheet

MATERIAL ID:

EPO-TEK[®] H61 Unfilled

Date: 08/2009

Per:

Rev: IV

Material Description:

A single component, high Tg, electrically insulating epoxy adhesive for semiconductor, microelectronic, and opto-electronic packaging applications. It is a liquid version of EPO-TEK[®] H61.

Number of Components:

Single

Mix Ratio by weight:

N/A

Cure Schedule (minimum)

150°C/30 Minutes - 120°C/60 Minutes

Specific Gravity:

1.22 --- Part A: Part B:

Pot Life:

28 Days

Shelf Life:

6 months refrigerated

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour*
 * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
*Color (before cure):	Clear/Light Yellow	Weight Loss:	
*Consistency:	Pourable liquid	@ 200°C:	0.38 %
*Viscosity (23°C):		@ 250°C:	0.64 %
@ 100 rpm	2,000 - 4,000 cPs	@ 300°C:	0.84 %
Thixotropic Index:	N/A	Operating Temp:	
*Glass Transition Temp:	≥ 110 °C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	Continuous:	- 55°C to + 200°C
Coefficient of Thermal Expansion (CTE):		Intermittent:	- 55°C to + 300°C
Below Tg:	49 x 10 ⁻⁶ in/in°C	Storage Modulus @ 23°C:	290,029 psi
Above Tg:	150 x 10 ⁻⁶ in/in°C	Ion Content:	
Shore D Hardness:	83	Cl ⁻ :	12 ppm
Lap Shear @ 23°C:	758 psi	NH ₄ ⁺ :	
Die Shear @ 23°C:	≥ 15 Kg / 5,100 psi	Na ⁺ :	275 ppm
Degradation Temp:	420 °C	K ⁺ :	15 ppm
		*Particle Size:	N/A

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A	Dielectric Constant (1KHz):	3.63
Volume Resistivity @ 23°C:	≥ 1 x 10 ¹³ Ohm-cm	Dissipation Factor (1KHz):	0.007

OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	N/A
Index of Refraction:	1.5464 @ 589 nm

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